Name of Person Signing

FORM PTO-1595 (Modified) (Rev. 03-01)

02-22-2006



Docket No.: 16489

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U.S. DEPARTMENT OF COMMERCE

OMB No. 0651-0027 (exp.5/31/2002) P08/REV03			Pa	atent and Trademark	Office
Tab settings → → → ▼	103182	100	7	▼ ▼	
To the Director of the United States Patent	t and Trademark Office	: Please record the at	tached original document	ts or copy thereof.	
1. Name of conveying party(ies): Lim Siong San Neo Mok Choon Kevin Lim Kelvin Yeow Additional names(s) of conveying party(ies)	☐ Yes ⊠ No		ess of receiving party(ie	es):	306
				967 173	021
3. Nature of conveyance:				2 +	
☑ Assignment	erger	Street Address:	2700 North First Stree	<u>t</u>	
☐ Security Agreement ☐ CI	hange of Name				
Other		City: San Jose	State:	<u>CA</u> ZIP: 9513	34
Execution Date: 02/09/2006		Additional name(s) &	k address(es) attached?	☐ Yes 🗵 No)
A. Patent Application No.(s)		B. Patent I		02/09/2006	
Add	ditional numbers attach	ned? 🗌 Yes 🗵	No	_	
Name and address of party to whom corrections document should be mailed:	espondence	6. Total number of	applications and paten	its involved:	1
Name: Julio Loza		7. Total fee (37 CF	FR 3.41):\$	40.00	
Internal Address: Loza & Loza 22/23/2006 DRYRNE 00000135 192090 11353725			Any excess or insufficie debited to deposit accor		
01 FC:8021 (40.00 DA		☑ Authorized t	o be charged to deposi	t account	
Street Address: 6285 Spring Street #327N	N	8. Deposit account	number:		
City: Long Beach State: C			py of this page if paying by d	deposit account)	
 Statement and signature. To the best of my knowledge and belief, to of the original document. Michael Fedrick 		SE THIS SPACE tion is true and corre	ect and any attached co		у

Signature

Total number of pages including cover sheet, attachments, and document:

Date

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby
acknowledged, we, the undersigned:
Lim Siong San, residing at Blk 163, #12-84, Yung Ping Road, Singapore 610163
Neo Mok Choon, residing at 802 Thomson Road, #07-07, Singapore 298187
Kevin Lim, residing atBlk 340, #08-593, Woodlands Ave 1, Singapore 730340
Kelvin Yeow, residing at 18 Sin Ming Walk, #09-03, Singapore 575569
Tan Kwang Chiah, residing at Blk 665A, #10-170, Jurong West St. 64, Singapore 641665
have invented certain new and useful improvements disclosed in United States Paten
Application No, filed, hereby sell, assign, and
transfer to:

SANMINA-SCI CORPORATION

a Corporation of Delaware, having a principal place of business at 2700 North First Street, San Jose, CA 95134 ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent that has been executed by the undersigned prior hereto or concurrently herewith on the dates indicated below and is entitled:

METHOD AND PROCESS FOR EMBEDDING CONDUCTIVE ELEMENTS IN A DIELECTRIC LAYER

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries of any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States and/or Patent Cooperation Treaty (PCT) application; and in all rights of priority under the International Convention for the Protection of

Page I of 2

Industrial Property for every country in the Union; agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been nor will be made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

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Lacn	Inventor:	riease	Sign	and	Date	perom:

Date:	09 Feb 2006
Date:	09 Feb 2006
Date <u>:</u>	09 Feb 2006
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Date:	09 Feb 2006

RECORDED: 02/13/2006

Signed:		_
	Lim Siong San	
Signed:	M	
	Neo Mok Choon	
Signed:	Stellen	
Signed:	KevirLim	
	Kelvin Keow	
Signed:	GC1001.	
	Tan Kwang Chiah	

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